SZ DJI TECHNOLOGY CO., LTD

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DECLARATION OF SIMILARITY

Date: 2020-09-25

FEDERAL COMMUNICATIONS COMMISSION

Authorization and Evaluation Division

7435 Oakland Mills Road

Columbia, MD 21046

Dear Sir or Madam:

We,SZ DJI TECHNOLOGY CO., LTD, hereby declare that theproduct:DJI FPV Drone, FCC ID:SS3-FD1W4K2006.The new version product(configurations #2) is electrically identical with the old version product(configurations #1) which was tested by BACL with the same product name ,model name and FCC ID.

A description of the differences and that are declared similar areas follows:

Schematic

The differences of the schematic between the new version and the old version of the drone are as follows

1. the main board of the old version of the drones uses CPU and DDR based on System in Package (SIP)technology, whilethe new version of the drone uses separated CPU and DDR. The hardware design of the two is completely consistentonly the PCB layout is a little different

2. The 4 page of the schematic diagram of the old version shows the hardware design of the SIP scheme of the core system. Among them, the part number of the SIP device is U1. It actually contains a circuit composed of a SOC, two LPDDR4, and a number of resistance capacitors and magnetic beads. The circuit is consistent with the (pg. 2) described at the new version schematic

3. The power design of the core system on the older version of the schematic (pg. 3) is almost consistent with the new version of the schematic (pg. 4). The only difference is the new version schematic removes two bucks and sever capacitors and resistors that not used on the old version schematic

PCB

The main change of the new version of the core board is that the core system has been changed from the design of SIP packaged devices to the design of discrete devices . Thus the changes of the new core board are concentrated on the SOC of the core system and the layout of the supporting devices (like LPDDR4 and EMMC) . Besides, the BOM almost has not changed due to the number of devices used in SIP packaged devices and discrete devices are basically the same.
There is no change in the radio frequency circuit.

Please contact me should there be need for any additional clarification or information.

Best Regards,

Signature:
Printed Name:wang fajia
Title:PM